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## 2SA1096, 2SA1096A

## Silicon PNP epitaxial planar type

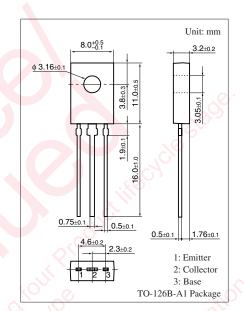
For low-frequency power amplification Complementary to 2SC2497, 2SC2497A

#### ■ Features

- Output of 5 W can be obtained by a complementary pair with 2SC2497 and 2SC2497A
- TO-126B package which requires no insulation plate for installation to the heat sink

### ■ Absolute Maximum Ratings $T_a = 25^{\circ}C$

3.7		
V <sub>CBO</sub>	-70	V
$V_{CEO}$	-50	V
	-60	
$V_{EBO}$	-5	V
$I_{C}$	-2	Α
I <sub>CP</sub>	-3	A
P <sub>C</sub>	1.2	w
T <sub>j</sub>	150	°C
T <sub>stg</sub>	-55 to +150	o °C
	$V_{EBO}$ $I_{C}$ $I_{CP}$ $P_{C}$ $T_{j}$	V <sub>CEO</sub>



### ■ Electrical Characteristics T<sub>a</sub> = 25°C ± 3°C

Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emit	ter open)	$V_{CBO}$	$I_{\rm C} = -1 \text{ mA}, I_{\rm E} = 0$	-70			V
Collector-emitter voltage	2SA1096	$V_{CEO}$	$I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$	-50			V
(Base open)	2SA1096A		all dis as as	-60			
Collector-base cutoff current (En	nitter open)	$I_{CBO}$	$V_{CB} = -20 \text{ V}, I_E = 0$			-1	μΑ
Collector-emitter cutoff current (I	Base open)	$I_{CEO}$	$V_{CE} = -10 \text{ V}, I_B = 0$			-100	μΑ
Emitter-base cutoff current (Collector open)		$I_{EBO}$	$V_{EB} = -5 \text{ V}, I_C = 0$			-10	μΑ
Forward current transfer ratio	o *1,2	$h_{FE}$	$V_{CE} = -5 \text{ V}, I_{C} = -1 \text{ A}$	80		220	_
Collector-emitter saturation	voltage	V <sub>CE(sat)</sub>	$I_C = -1.5 \text{ A}, I_B = -0.15 \text{ A}$			-1	V
Base-emitter saturation volta	ige	V <sub>BE(sat)</sub>	$I_C = -1.5 \text{ A}, I_B = -0.15 \text{ A}$			-1.5	V
Transition frequency		$f_T$	$V_{CB} = -5 \text{ V}, I_E = 0.5 \text{ A}, f = 200 \text{ MHz}$		150		MHz
Collector output capacitance		C <sub>ob</sub>	$V_{CB} = -20 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		55		pF
(Common base, input open of	circuited)						

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

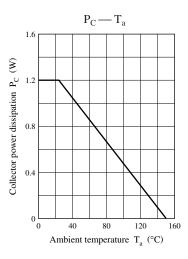
2. \*1: Pulse measurement

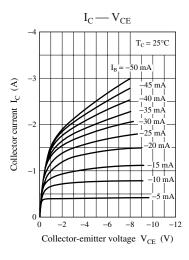
\*2: Rank classification

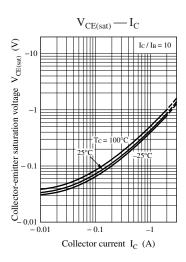
Rank	Q	R
$h_{FE}$	80 to 160	120 to 220

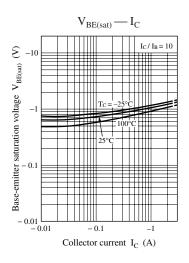
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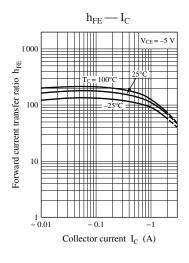
## **Panasonic**

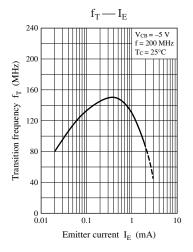


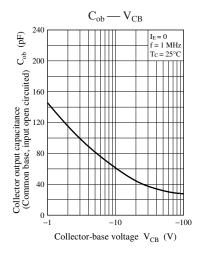


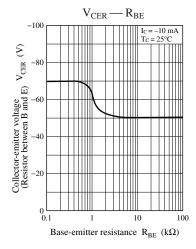


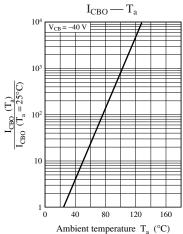




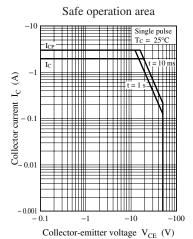








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